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5/12/06

METHOD OF MANUFACTURING FINE METAL PARTICLES, ~~SUBSTANCE~~  
~~CONTAINING FINE METAL PARTICLES, AND PASTE SOLDER COMPOSITION~~

CROSS-REFERENCE TO RELATED APPLICATIONS

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5           This application claims priority to the United States Patent Application Serial  
Number 10/106,646 filed on March 26, 2002, <sup>abandoned,</sup> which is a U.S. National Phase of Japan  
Application Number 2001-092273 filed March 28, 2001; Japan Application Number  
2001-288778 filed September 21, 2001; and Japan Application Number 2001-395566 filed  
December 27, 2001.

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BACKGROUND OF THE INVENTION

          The present invention relates to a method of manufacturing fine metal particles  
such as solder particles, to a fine metal particles-containing substance containing such fine  
metal particles, and to a paste solder composition comprising such a fine metal  
15 particles-containing substance.

          In recent years, concomitant with an increasing trend to multi-functionalize the  
wiring board of electronic devices as well as with an increasing trend of miniaturization, i.e.  
the reduction of the size and weight of electronic devices, a surface mounting technique  
has now been quickly advanced, so that it is now desired, for the purpose of realizing a  
20 high density packaging such as the surface mounting of electronic device, to develop a  
solder paste or other kinds of soldering materials and a soldering method, which are not